Materials Declaration

Package	PLCC
Body Size	24 x 24
LeadCount	68
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.0	3.42 E+00	688951
Multi-aromatic Resin	14.0	5.57 E-01	112155

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.9	9.20 E-01	185187
Zr	0.1	9.21 E-04	185

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.31 E-03	465

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.43 E-02	6909

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.99 E-03	601

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.32 E-02	4664

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70.00	3.07 E-03	618
Diglycidylether of bisphenol-F	10.00	4.39 E-04	88
Resin	7.00	3.07 E-04	62
Amine	5.0	2.19 E-04	44
Gamma Butyrolactone	5.0	2.19 E-04	44
Mixed aryl allyl glycidyl compounds	3.0	1.32 E-04	27

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA 3050B. ICP-AES.
Cd	None Detected	EPA 3050B. ICP-AES.
Hg	None Detected	EPA 3052B. ICP-AES.
Cr+6	None Detected	EPA 3060A. UV-VIS
PBB	None Detected	Analysis was performed by GC/MS.
PBDE	None Detected	Analysis was performed by GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	3	US EPA 3052. ICP-OES.
Cd	None Detected	US EPA 3052. ICP-OES.
Hg	None Detected	US EPA 3052. ICP-OES.
Cr+6	None Detected	US EPA 3060A & 7196A. UV-VIS.
PBB	None Detected	Analysis was performed by GC/MS.
PBDE	None Detected	Analysis was performed by GC/MS.

Package Totals

Weight (g)	PPM
4.97 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

Materials Declaration

Package	PLCC
Body Size	24 x 24
LeadCount	68
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Cresol Novolac	12	3.99 E-01	97287
SiO2 Filler	78	2.60 E+00	632364
Phenol Novolac	7.8	2.60 E-01	63236
Antimony_Sb2O3	3	9.98 E-02	24322
Brominated Resin	2	6.66 E-02	16214
Carbon Black	0.2	6.66 E-03	1621

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.9	6.03 E-01	146854
Zr	0.1	6.03 E-04	147

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.02 E-03	492

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.42 E-02	8327
Pb	15	6.03 E-03	1470

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.42 E-03	833

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	2.35 E-02	5718

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.14 E-03	279
Ag Filler	75	3.43 E-03	836

Molding Compound

Item	PPM	Method
Pb	5	US EPA Method #3050B (ICPAES)
Cd	<2	BS EN 1122:2001B (ICPAES)
Hg	<2	Mercury Analyser
Cr+6	<2	US EPA method #3060A (UV)

Die Attach Paste

Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Package Totals

Weight (g)	PPM
4.11 E+00	1000000

STS-P-A

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